



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140219003
Qualification of TI Clark, Carsem Suzhou and HNT as Additional
Assembly/Test Site for Select Devices
Change Notification / Sample Request

Date: 3/3/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140219003
Attachment: 1

Products Affected:

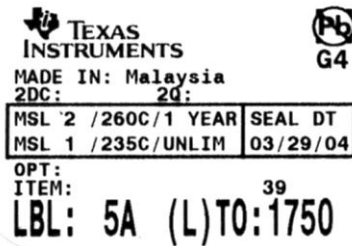
The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ2022ADBZR	null
TPS62080DSGT	null
TPS62081DSGT	null
TPS62082DSGT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140219003			PCN Date:	03/03/2014
Title:	Qualification of TI Clark, Carsem Suzhou and HNT as Additional Assembly/Test Site for Select Devices				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	06/03/2014	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
☒	Assembly Site				
☒	Test Site				
PCN Details					
Description of Change:					
Qualification of TI Clark, Carsem Suzhou and HNT as Additional Assembly/Test Site for Select Devices. No material differences between Assembly/Test sites.					
		From	To		
Group 1 Device		NSE	TI - Clark		
Group 2 Device		TI - Clark	Carsem Suzhou		
Group 3 Device		NSE	HNT		
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Group 1 device : NSE to TI Clark					
Assembly Site					
NSE Thailand	Assembly Site Origin (22L)		ASO: NSE		
TI Clark Philippines	Assembly Site Origin (22L)		ASO: QAB		
ASSEMBLY SITE CODES: NSE =J, TI-Clark =I					
Group 2 device : TI Clark to Carsem Suzhou					
Assembly Site					
TI Clark Philippines	Assembly Site Origin (22L)		ASO: QAB		
Carsem Suzhou	Assembly Site Origin (22L)		ASO: CSZ		
ASSEMBLY SITE CODES: TI-Clark =I, Carsem Suzhou = F					
Group 3 device : NS2 to HNT					
Assembly Site					
UTAC Thailand	Assembly Site Origin (22L)		ASO: NS2		
Hana Thailand	Assembly Site Origin (22L)		ASO: HNT		
ASSEMBLY SITE CODES: UTAC =B, HANA =H					

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO:USA
(22L) AS0: MLA (23L) ACO: MYS

Group 1 Product Affected:

TLV62080DSGR	TPS62080DSGR	TPS62081DSGR	TPS62082DSGR
TLV62080DSGT	TPS62080DSGT	TPS62081DSGT	TPS62082DSGT

Group 2 Product Affected:

TPS22967DSGR	TPS22967DSGT
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Group 3 Product Affected:

BQ2022ADBZR	HPA01220DBZR	SN239089ADBZRG4
BQ2022ADBZRG4	HPAPS004ADBZR	SN239089DBZR
HPA00649DBZR	SN239089ADBZR	SN239089DBZRG4

Group 1 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TPS62750DSK (MSL1-260C)

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	10-DSK, WSON	Mount Compound:	4207768
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot# 1	Lot# 2	Lot# 3
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150 (500 cycles)	77/0	77/0	76/0
**High Temp. Storage Bake	170C (420 Hrs)	129/0	128/0	129/0
Surface Mount Solderability	8 Hrs Steam Age-Pb Free	22/0	22/0	22/0
Salt Atmosphere	-	22/0	22/0	22/0
Manufacturability (MQ)		Pass	Pass	Pass
Moisture Sensitivity	L1-260C	12/0	12/0	12/0

** - Preconditioning sequence: Level 1-260C.

Qual Vehicle 2: TLV70028DSE (MSL1-260C)

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	6-DSE, WSON	Mount Compound:	4207768
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia. Cu

Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot# 1	Lot# 2	Lot# 3
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150 (500 cycles)	77/0	77/0	76/0
**High Temp. Storage Bake	170C (420 Hrs)	110/0	110/0	110/0
Surface Mount Solderability	8 Hrs Steam Age-Pb Free	22/0	22/0	22/0
Salt Atmosphere	-	22/0	22/0	22/0
Manufacturability (MQ)		Pass	Pass	Pass
Moisture Sensitivity	L1-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 1-260C.				
Qual Vehicle 3: TPS51980ARTV (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	32-RTV, WQFN	Mount Compound:	4207768	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot# 1	Lot# 2	Lot# 3
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	76/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	-
**- Preconditioning sequence: Level 2-260C.				

Group 2 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle 1: TPS22965DSGR (MSL2-260C)				
Package Construction Details				
Assembly Site:	Carsem Suzhou	Mold Compound:	441086	
# Pins-Designator, Family:	8-DSG, SON	Mount Compound:	435143	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	2.0 Mil Dia. Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test		Conditions	Sample Size / Fail	
Electrical Characterization		-	Pass	
X-RAY		(top side only)	5/0	
Manufacturability (MQ)		(Assembly)	Pass	
Moisture Sensitivity		L2-260C	13/0	
**- Preconditioning sequence: Level 2-260C.				
Qual Vehicle 2: TPS51123RGER (MSL2-260C)				
Package Construction Details				
Assembly Site:	Carsem Suzhou	Mold Compound:	441086	
# Pins-Designator, Family:	24-RGE, VQFN	Mount Compound:	435143	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	

Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot# 1	Lot# 2	Lot# 3
**Steady-state Life	125C (1000 Hrs)	37/0	39/0	39/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150 (500 cycles)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 Hrs)	110/0	110/0	110/0
Surface Mount Solderability	Pb Free/Solder	22/0	22/0	22/0
Salt Atmosphere	-	22/0	22/0	22/0
Manufacturability (MQ)		Pass	Pass	Pass
Moisture Sensitivity	L2-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 2-260C.				

Group 3 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: TLV431AIDBZ6 (MSL1-260C)				
Package Construction Details				
Assembly Site:	HNT	Mold Compound:	450179	
# Pins-Designator, Family:	3-DBZ, SOT-23	Mount Compound:	400154	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia. Au	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot# 1	Lot# 2	Lot# 3
**Steady-state Life	150C (300 Hrs)	116/0	116/0	116/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150 (1000 cycles)	77/0	77/0	76/0
**Thermal Shock	-65/150 (1000 cycles)	76/0	77/0	76/0
**High Temp. Storage Bake	150C (1000 Hrs)	45/0	45/0	45/0
Solderability	8 Hrs Steam Age	22/0	22/0	22/0
Flammability	(UL 94V-0)	5/0	5/0	5/0
Flammability	(UL-1694)	5/0	5/0	5/0
Flammability	(IEC 695-2-2)	5/0	5/0	5/0
X-RAY	(top side only)	5/0	5/0	5/0
Salt Atmosphere	-	22/0	22/0	22/0
Manufacturability (MQ)		Pass	Pass	Pass
Moisture Sensitivity	L1-260C	4/0	4/0	4/0
**- Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com